

Low k Interlevel Dielectric Layer Fabrication Methods

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TECHNICAL FIELD

This invention relates to methods of forming low k interlevel dielectric layers.

BACKGROUND OF THE INVENTION

In methods of forming integrated circuits, it is frequently desired to electrically isolate components of the integrated circuits from one another with an insulative material. For example, conductive layers can be electrically isolated from one another by separating them with an insulating material. Insulating material received between two different elevation conductive or component layers is typically referred to as an interlevel dielectric material. Also, devices which extend into a semiconductive substrate can be electrically isolated from one another by insulative materials formed within the substrate between the components, such as for example, trench isolation regions.

One typical insulative material for isolating components of integrated circuits is silicon dioxide, which has a dielectric constant of about 4. Yet in many applications, it is desired to utilize insulative materials having dielectric constants lower than that of silicon dioxide to reduce parasitic capacitance from occurring between conductive components separated by the insulative material. Parasitic capacitance

1 reduction continues to have increasing importance in the semiconductor
2 fabrication industry as device dimensions and component spacing
3 continues to shrink. Closer spacing adversely effects parasitic
4 capacitance.

5 *Subh B.*
6 One way of reducing the dielectric constant of certain inherently
7 insulative materials is to provide some degree of carbon content therein.
8 One example technique for doing so has recently been developed by
9 Trikon Technology of Bristol, UK which they refer to as Flowfill™
10 Technology. Where more carbon incorporation is desired, methylsilane
11 in a gaseous form and H₂O₂ in a liquid form are separately introduced
12 into a chamber, such as a parallel plate reaction chamber. A reaction
13 between the methylsilane and H₂O₂ can be moderated by introduction
14 of nitrogen into the reaction chamber. A wafer is provided within the
15 chamber and ideally maintained at a suitable low temperature, such as
16 0° C, at an exemplary pressure of 1 Torr to achieve formation of a
17 methylsilanol structure. Such structure/material condenses on the wafer
18 surface. Although the reaction occurs in the gas phase, the deposited
19 material is in the form of a viscous liquid which flows to fill small gaps
20 on the wafer surface. In applications where deposition thickness
21 increases, surface tension drives the deposited layer flat, thus forming
22 a planarized layer over the substrate.

23 The liquid methylsilanol is converted to a silicon dioxide structure
24 by a two-step process occurring in two separate chambers from that in
which the silanol-type structure was deposited. First, planarization of

1 the liquid film is promoted by increasing the temperature to above 100°
2 C, while maintaining the pressure at about 1 Torr, to result in
3 solidification and formation of a polymer layer. Thereafter, the
4 temperature is raised to approximately 450°C, while maintaining a
5 pressure of about 1 Torr, to form $(CH_3)_xSiO_y$. The $(CH_3)_xSiO_y$ has
6 a dielectric constant of less than or equal to about 3, and is
7 accordingly less likely to be involved in parasitic capacitance than silicon
8 dioxide and/or phosphorous doped silicon dioxide.

9 Nevertheless, it would be desirable to develop improved methods
10 for reducing parasitic capacitance of interlevel dielectric layers which
11 comprise carbon and regardless of the method of manufacture of such
12 layers.

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15 **SUMMARY**

16 The invention comprises methods of forming low k interlevel
17 dielectric layers. In one implementation, a low k interlevel dielectric
18 layer fabrication method includes providing a substrate having integrated
19 circuitry at least partially formed thereon. An oxide comprising
20 interlevel dielectric layer comprising carbon and having a dielectric
21 constant no greater than 3.5 is formed over the substrate. After
22 forming the carbon comprising dielectric layer, it is exposed to a plasma
23 comprising oxygen effective to reduce the dielectric constant to below
24 what it was prior to said exposing.

1 In one implementation, a low k interlevel dielectric layer
2 fabrication method includes providing a substrate having integrated
3 circuitry at least partially formed thereon. In a chamber, an interlevel
4 dielectric layer comprising carbon and having a dielectric constant no
5 greater than 3.5 is plasma enhanced chemical vapor deposited over the
6 substrate at subatmospheric pressure. After forming the carbon
7 comprising dielectric layer, it is exposed to a plasma comprising oxygen
8 at a subatmospheric pressure effective to reduce the dielectric constant
9 by at least 10% below what it was prior to said exposing. The
10 exposing occurs without removing the substrate from the chamber
11 between the depositing and the exposing, and pressure within the
12 chamber is maintained at subatmospheric between the depositing and the
13 exposing.

14 In one implementation, a low k interlevel dielectric layer
15 fabrication method includes providing a substrate having integrated
16 circuitry at least partially formed thereon. An interlevel dielectric layer
17 comprising a compound having silicon bonded to both nitrogen and an
18 organic material and having a dielectric constant no greater than 8.0
19 over is formed over the substrate. After forming the dielectric layer,
20 it is exposed to a plasma comprising nitrogen effective to reduce the
21 dielectric constant to below what it was prior to said exposing.

1 **BRIEF DESCRIPTION OF THE DRAWINGS**

2 Preferred embodiments of the invention are described below with
3 reference to the following accompanying drawings.

4 Fig. 1 is a diagrammatic view of a semiconductor wafer fragment
5 at one processing step in accordance with the invention.

6 Fig. 2 is a view of the Fig. 1 wafer at a processing step
7 subsequent to that shown by Fig. 1.

8 **DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS**

9 This disclosure of the invention is submitted in furtherance of the
10 constitutional purposes of the U.S. Patent Laws "to promote the
11 progress of science and useful arts" (Article 1, Section 8).

12 Referring to Fig. 1, an exemplary semiconductor wafer fragment
13 or substrate in process is indicated generally with reference numeral 10.
14 In the context of this document, the term "semiconductor substrate" or
15 "semiconductive substrate" is defined to mean any construction comprising
16 semiconductive material, including, but not limited to, bulk
17 semiconductive materials such as a semiconductive wafer (either alone
18 or in assemblies comprising other materials thereon), and semiconductive
19 material layers (either alone or in assemblies comprising other
20 materials). The term "substrate" refers to any supporting structure,
21 including, but not limited to, the semiconductive substrates described
22 above.

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1 Substrate 10 comprises a bulk monocrystalline silicon substrate 12
2 having trench isolation oxide regions 14 formed therein. Integrated
3 circuitry is at least partially formed thereon in the illustrated example
4 in the form of a pair of transistors 16 and 18. Transistors 16 and 18
5 can comprise conventional constructions, such as overlying layers of gate
6 oxide, polysilicon and silicide. Insulative spacers 20 are formed adjacent
7 to transistor gates 16 and 18. Conductively doped diffusion regions 22, 24
8 and 26 are formed within substrate 12 and proximate gates 16 and 18.

9 Referring to Fig. 2 and in accordance with but one aspect of the
10 invention, an interlevel dielectric layer 30 comprising carbon and having
11 a dielectric constant no greater than 3.5 is formed over the Fig. 1
12 substrate where layer 30 comprises oxide material. Such layer might be
13 formed by a number of methods. One example preferred method
14 includes the Flowfilltm technique referred to above, whereby the formed
15 interlevel dielectric level comprises or ultimately consists essentially of
16 $(CH_3)_xSiO_y$, where x ranges from 1 to 3, and y ranges from 0-2. Such
17 provides but one example where the dielectric layer formed comprises
18 silicon bonded to organic material. Other dielectric layers, as well as
19 the same or other layers, fabricated by different methods are also
20 contemplated.

21 By way of example only, example preferred alternate methods of
22 producing an interlevel dielectric layer at this point in the process are
23 now described. Such encompass methods of forming insulative materials
24 comprising carbon, silicon and oxygen. In one example, a first gaseous

1 precursor compound comprising carbon and silicon is combined with a
2 second gaseous precursor compound comprising oxygen to form a second
3 compound comprising carbon, silicon and oxygen. The first compound
4 can comprise, for example, $(CH_3)_ySiH_x$, wherein y is an integer of from
5 1 to 4 and x is an integer from 0 to 3. The second precursor
6 compound is an oxygen-containing moiety that is preferably a "dry"
7 compound (i.e., a compound that does not either contain water or
8 decompose to form water), and can comprise, for example, N_2O , or an
9 activated oxygen species (e.g., high energy O_2 , monatomic oxygen, or
10 oxygen radicals). Such provides but one example process whereby water
11 formation is avoided. In one example, the oxygen-containing moiety is
12 generated by exposing O_2 to ultra-violet light (a process which can
13 generate, for example, activated oxygen species in the form of O_3). In
14 another aspect, the oxygen-containing moiety is generated by exposing
15 an oxygen-containing gas (e.g., O_3 , O_2 , N_2O , CO, or CO_2) to a plasma.
16 The plasma can be within the reaction chamber or remote from the
17 chamber (i.e., not in the chamber). In another example, a compound
18 comprising silicon, carbon and oxygen is formed by reaction of SiH_4
19 with an organic compound comprising oxygen (e.g., CO or CO_2).

20 In a more specific example, methylsilane or trimethylsilane is
21 combined with N_2O in a reaction chamber. A pressure within the
22 chamber is maintained at from about 300 mTorr to about 30 Torr, and
23 is preferably maintained at from about 1 Torr to about 10 Torr. An

1 exemplary reaction chamber comprises a spacing from about 400 mils
2 to about 600 mils with methylsilane being flowed into the chamber at
3 a rate from about 25 standard cubic centimeters per minute (scm) to
4 about 2000 sccm (preferably at from about 50 sccm to about 250 sccm).
5 The N₂O is flowed into the reaction chamber at a rate from about 50
6 sccm to about 3000 sccm (preferably at a rate from about 100 sccm to
7 about 1500 sccm, and more preferably at a rate of from about 500
8 sccm to about 1200 sccm), and, additionally, helium is flowed into the
9 reaction chamber at a rate of about 500 sccm to about 5000 sccm
10 (preferably from 1000 sccm to about 3000 sccm). A radio frequency
11 (RF) power within the chamber is maintained at from about 50 watts
12 to about 500 watts, and preferably from about 100 watts to about 200
13 watts. The semiconductor substrate (such as a monocrystalline silicon
14 wafer) is provided within the chamber and maintained at a temperature
15 from about 25°C to about 450°C.

16 The above-described processing forms (CH₃)_xSiO_y over a substrate.
17 The concentration of methyl groups within the (CH₃)_xSiO_y is typically
18 from about 10% to about 50% (mole percent), i.e., where x equals or
19 ranges from about 1 to about 3, and y ranges from 0 to about 2.
20 Alternately by way of example only, x can be from about 0.1 to about
21 1, i.e., the concentration of methyl groups can be from about 5% to
22 about 50% molar. In a particular example, a plasma can be generated
23 within the chamber at a RF power of from about 50 watts to about
24 500 watts (preferably from about 80 watts to about 200 watts).

Such describes but one example process of forming an interlevel dielectric layer, here by chemical vapor deposition with or without plasma in a chemical vapor deposition chamber. In but another considered example, a gaseous precursor compound is introduced into a chemical vapor deposition reaction chamber and subjected to a plasma treatment. A semiconductor substrate is provided in the chamber, and material comprising carbon and silicon is deposited from the plasma-treated precursor compound to over the substrate. After the material is deposited, it is exposed to an oxygen containing moiety and converted to a second material comprising silicon, carbon and oxygen.

In a more specific example, methylsilane is flowed into a reaction chamber at a pressure of from 300 mTorr to about 30 Torr (preferably from about 1 Torr to about 10 Torr) and subjected to a plasma formed at a power of from about 50 watts to about 500 watts (preferably from 100 watts to about 200 watts). A semiconductor substrate is provided in the reaction chamber and maintained at a temperature of about 0° C to about 600° C. The plasma treated methylsilane deposits a material comprising methyl groups and silicon over the substrate. The deposited material is then exposed to an oxygen-containing moiety to convert the material to $(CH_3)_xSiO_y$. Accordingly in this example from the oxygen exposure, a whole of the deposited dielectric layer is transformed from one base chemistry (i.e., that comprising a nondescript combination of methyl groups and silicon) to another base chemistry (i.e., $(CH_3)_xSiO_y$) by the oxygen exposure. The oxygen-containing

1 moiety is preferably in gaseous form, and can comprise, for example
2 ozone, O₂ and/or N₂O. In particular embodiments, the oxygen-
3 containing moiety is subjected to plasma, heat or ultra-violet light. The
4 oxygen treatment preferably occurs at a pressure of from about 300
5 mTorr to about 1 atmosphere, with the deposited material being
6 maintained at a temperature of from about 0° C to about 600°C during
7 the oxygen treatment to convert the base chemistry to (CH₃)_xSiO_y.

8 The above-described processings are again only example preferred
9 techniques of forming the preferred interlevel dielectric layer material
10 comprising carbon, here in the form of CH₃, and here producing a
11 preferred layer of (CH₃)_xSiO_y. Alternate interlevel dielectric materials
12 comprising carbon are of course contemplated. Further and by way of
13 example only, the deposited interlevel dielectric layer at this point in
14 the process might comprise silicon atoms bonded to both organic
15 material and nitrogen, for example as described below.

16 After forming carbon comprising dielectric layer 30, in but one
17 aspect of the invention, such layer is exposed to a plasma comprising
18 oxygen effective to reduce the dielectric constant to below what it was
19 prior to said exposing. Preferably, the exposing is at subatmospheric
20 pressure to reduce the dielectric constant by at least 10%, and even
21 more preferably by at least 15%, below what it was prior to said
22 exposing. In a most preferred embodiment, the method by which the
23 interlevel dielectric layer is initially formed is by plasma enhanced
24 chemical vapor deposition in a chamber, with the subsequent exposing

of the plasma occurring in subatmospheric pressure in the same chamber. Further, the substrate is preferably not removed from the chamber between the depositing and the exposing. Further, the pressure within the chamber is preferably maintained at subatmospheric between the depositing and the exposing. Further, the exposing is ideally effective to increase stability of the dielectric constant to variation from what the stability was prior to the exposing. Specifically, stability of the dielectric constant of interlevel dielectric materials can have a tendency to increase over time or when exposed to subsequent thermal processing of at least 400°C. Ideally, the exposing is also effective to increase the stability of the dielectric constant of such film.

Exemplary processing in accordance with the invention has been achieved whereby a predominately $(CH_3)_xSiO_y$ interlevel dielectric layer after the exposing had a dielectric constant reduced from 3.0 to about 2.5 or 2.0.

The preferred wafer surface temperature during the exposing is always less than or equal to 550°C, with the exposing also preferably being conducted at subatmospheric pressure. The oxygen comprising plasma is preferably derived at least in part from at least one of O₂, O₃, N₂O, and NO_x. Preferred parameters for the exposing in a dual plate capacitively coupled reactor include an RF power range of from 300 to 1000 watts, a pressure range of from 1 Torr to 6 Torr, a temperature range of from 100°C to 450°C, a spacing between the plates of from 400 to 600 mils, an oxygen gas exposure flow of from

1 500 to 1500 sccm, an inert gas flow (i.e., He and/or Ar) of from 200
2 sccm to 800 sccm, and a treatment time of from 20 to 100 to more
3 seconds. It is a preferred intent of the exposing to further not
4 transform a whole of all of the dielectric layer from one base chemistry
5 to another base chemistry by the exposing. An outermost portion of
6 the exposed layer might experience a slight reduction in carbon content,
7 but otherwise that portion and the whole of the layer is not
8 transformed from one fundamental material to another even in spite of
9 the low k reducing or resulting property. In one preferred aspect of
10 the invention, the exposing comprises at least 20 seconds of processing
11 time. More preferably and in preferred sequence, the processing
12 comprises at least 40 seconds, 60 seconds, 80 seconds, and 100 seconds
13 of oxygen containing plasma exposure. The plasma exposing is
14 preferably ineffective to appreciably etch the interlevel dielectric layer.

15 Where the invention is conducted *in situ* in a plasma enhanced
16 chemical vapor deposition chamber subsequent to the deposition, the
17 exposing might comprise substantially ceasing feeding of one of the
18 reactive gases while maintaining a feed of one of the precursors which
19 comprises oxygen, and thereby maintaining plasma conditions from the
20 deposition through an extended exposure time with the oxygen containing
21 precursor to achieve the exposing effect.

22 In another considered aspect of the invention, a nitride comprising
23 interlevel dielectric layer 30 is formed over the substrate to also
24 comprise carbon and having a dielectric constant no greater than 8.0.

1 More preferred, interlevel dielectric layer 30 comprises a compound
2 having silicon bonded to both nitrogen and an organic material and
3 having a dielectric constant no greater than 8.0. After forming such
4 dielectric layer, it is exposed to a plasma comprising nitrogen effective
5 to reduce the dielectric constant to below what it was prior to said
6 exposing, and preferably at least 15% below what it was prior to the
7 exposing. By way of example only, a preferred deposited interlevel
8 dielectric layer material comprises or consists essentially of
9 $(CH_3)_xSi_3N_{(4-x)}$, wherein x is greater than 0 and no greater than 4.
10 Such a composition can be formed by, for example, reacting inorganic
11 silane with one or more of ammonia (NH_3), hydrazine (N_2H_4), or a
12 combination of nitrogen (N_2) and hydrogen (H_2). The reaction can
13 occur with or without plasma. However, if the reaction comprises an
14 organic silane in combination with dinitrogen and dihydrogen, the
15 reaction preferably occurs in the presence of plasma.

16 An exemplary specific reaction is to combine methylsilane
17 (CH_3SiH_3) with NH_3 in the presence of a plasma to form
18 $(CH_3)_xSi_3N_{(4-x)}$. The exemplary reaction can occur, for example, under
19 the following conditions. A substrate is placed within a reaction
20 chamber of a reactor, and a surface of the substrate is maintained at
21 a temperature of from about 0°C to about 600°C. Ammonia and
22 methyl silane are flowed into the reaction chamber, and a pressure
23 within the chamber is maintained at from about 300 mTorr to about
24 30 Torr, with a plasma at a radio frequency (RF) power of from about

1 50 watts to about 500 watts. A product comprising $(CH_3)_xSi_3N_{(4-x)}$ is
2 then formed and deposited on the substrate.

3 Using this particular described example, it was found that the
4 product deposited from the described reaction consists essentially of
5 $(CH_3)_xSi_3N_{(4-x)}$, (wherein x is generally about 1). The $(CH_3)_xSi_3N_{(4-x)}$
6 is present in the product to a concentration of from greater than 0%
7 to about 50% (mole percent) and is preferably from about 10% to
8 about 20%. The amount of $(CH_3)_xSi_3N_{(4-x)}$ present in the product can
9 be adjusted by providing a feed gas of SiH_4 in the reactor in addition
10 to the CH_3SiH_3 , and by varying a ratio of the SiH_4 to the CH_3SiH_3 ,
11 and/or by adjusting RF power.

12 The above provides but only one example of forming an interlevel
13 dielectric layer comprising a compound having silicon bonded to both
14 nitrogen and an organic material. Other methods of forming the same
15 or different materials are of course contemplated.

16 After forming the dielectric layer, the nitrogen comprising plasma
17 to which the layer is exposed preferably comprises one or more of N_2 ,
18 NH_3 , N_2H_4 , N_2O , and NO_x . More preferably, the plasma exposing is
19 preferably void of oxygen atoms therein. Wherein the dielectric layer
20 is formed by chemical vapor deposition in a chamber, such as described
21 above, the exposing preferably occurs within the chamber without
22 removing the substrate from the chamber between the forming and the
23 exposing. Again, the plasma exposing like in the first described

1 example is preferably conducted to be ineffective to appreciably etch the
2 interlevel dielectric layer. Further, a whole of the dielectric layer
3 subjected to the exposing is preferably not transformed from one base
4 chemistry to another by the exposing. Preferred temperature, pressure,
5 power, space arrangements, flows, and treatment times are as described
6 above with respect to the first described embodiments.

7 In compliance with the statute, the invention has been described
8 in language more or less specific as to structural and methodical
9 features. It is to be understood, however, that the invention is not
10 limited to the specific features shown and described, since the means
11 herein disclosed comprise preferred forms of putting the invention into
12 effect. The invention is, therefore, claimed in any of its forms or
13 modifications within the proper scope of the appended claims
14 appropriately interpreted in accordance with the doctrine of equivalents.

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